

# 1. XBee/XBee-PRO OEM RF Modules

The XBee and XBee-PRO OEM RF Modules were engineered to meet IEEE 802.15.4 standards and support the unique needs of low-cost, low-power wireless sensor networks. The modules require minimal power and provide reliable delivery of data between devices.

The modules operate within the ISM 2.4 GHz frequency band and are pin-for-pin compatible with each other.



## 1.1. Key Features

### Long Range Data Integrity

XBee

- Indoor/Urban: up to 100' (30 m)
- Outdoor line-of-sight: up to 300' (100 m)
- Transmit Power: 1 mW (0 dBm)
- Receiver Sensitivity: -92 dBm

XBee-PRO

- Indoor/Urban: up to 300' (100 m)
- Outdoor line-of-sight: up to 1 mile (1500 m)
- Transmit Power: 100 mW (20 dBm) EIRP
- Receiver Sensitivity: -100 dBm

RF Data Rate: 250,000 bps

### Advanced Networking & Security

Retries and Acknowledgements  
 DSSS (Direct Sequence Spread Spectrum)  
 Each direct sequence channels has over 65,000 unique network addresses available  
 Source/Destination Addressing  
 Unicast & Broadcast Communications  
 Point-to-point, point-to-multipoint and peer-to-peer topologies supported  
 Coordinator/End Device operations

### Low Power

XBee

- TX Current: 45 mA (@3.3 V)
- RX Current: 50 mA (@3.3 V)
- Power-down Current: < 10  $\mu$ A

XBee-PRO

- TX Current: 215 mA (@3.3 V)
- RX Current: 55 mA (@3.3 V)
- Power-down Current: < 10  $\mu$ A

### ADC and I/O line support

Analog-to-digital conversion, Digital I/O  
 I/O Line Passing

### Easy-to-Use

No configuration necessary for out-of box RF communications  
 Free X-CTU Software (Testing and configuration software)  
 AT and API Command Modes for configuring module parameters  
 Extensive command set  
 Small form factor

**Free & Unlimited RF-XPert Support**

### 1.1.1. Worldwide Acceptance

**FCC Approval (USA)** Refer to Appendix A [p57] for FCC Requirements. Systems that contain XBee/XBee-PRO RF Modules inherit MaxStream Certifications.

ISM (Industrial, Scientific & Medical) **2.4 GHz frequency band**

Manufactured under **ISO 9001:2000** registered standards

XBee/XBee-PRO RF Modules are optimized for use in the **United States, Canada, Australia, Israel and Europe**. Contact MaxStream for complete list of government agency approvals.



## 1.2. Specifications

Table 1-01. Specifications of the XBee/XBee-PRO OEM RF Modules

Specification	XBee	XBee-PRO
<b>Performance</b>		
Indoor/Urban Range	up to 100 ft. (30 m)	Up to 300' (100 m)
Outdoor RF line-of-sight Range	up to 300 ft. (100 m)	Up to 1 mile (1500 m)
Transmit Power Output (software selectable)	1mW (0 dBm)	60 mW (18 dBm) conducted, 100 mW (20 dBm) EIRP*
RF Data Rate	250,000 bps	250,000 bps
Serial Interface Data Rate (software selectable)	1200 - 115200 bps (non-standard baud rates also supported)	1200 - 115200 bps (non-standard baud rates also supported)
Receiver Sensitivity	-92 dBm (1% packet error rate)	-100 dBm (1% packet error rate)
<b>Power Requirements</b>		
Supply Voltage	2.8 – 3.4 V	2.8 – 3.4 V
Transmit Current (typical)	45mA (@ 3.3 V)	If PL=0 (10dBm): 137mA(@3.3V), 139mA(@3.0V) PL=1 (12dBm): 155mA (@3.3V), 153mA(@3.0V) PL=2 (14dBm): 170mA (@3.3V), 171mA(@3.0V) PL=3 (16dBm): 188mA (@3.3V), 195mA(@3.0V) PL=4 (18dBm): 215mA (@3.3V), 227mA(@3.0V)
Idle / Receive Current (typical)	50mA (@ 3.3 V)	55mA (@ 3.3 V)
Power-down Current	< 10 $\mu$ A	< 10 $\mu$ A
<b>General</b>		
Operating Frequency	ISM 2.4 GHz	ISM 2.4 GHz
Dimensions	0.960" x 1.087" (2.438cm x 2.761cm)	0.960" x 1.297" (2.438cm x 3.294cm)
Operating Temperature	-40 to 85° C (industrial)	-40 to 85° C (industrial)
Antenna Options	Integrated Whip, Chip or U.FL Connector	Integrated Whip, Chip or U.FL Connector
<b>Networking &amp; Security</b>		
Supported Network Topologies	Point-to-point, Point-to-multipoint & Peer-to-peer	
Number of Channels (software selectable)	16 Direct Sequence Channels	12 Direct Sequence Channels
Addressing Options	PAN ID, Channel and Addresses	PAN ID, Channel and Addresses
<b>Agency Approvals</b>		
United States (FCC Part 15.247)	OUR-XBEE	OUR-XBEEPRO
Industry Canada (IC)	4214A XBEE	4214A XBEEPRO
Europe (CE)	ETSI	ETSI (Max. 10 dBm transmit power output)*
Japan	n/a	005NYCA0378 (Max. 10 dBm transmit power output)**

\* When operating in Europe: XBee-PRO RF Modules must be configured to operate at a maximum transmit power output level of 10 dBm. The power output level is set using the PL command. The PL parameter must equal "0" (10 dBm).

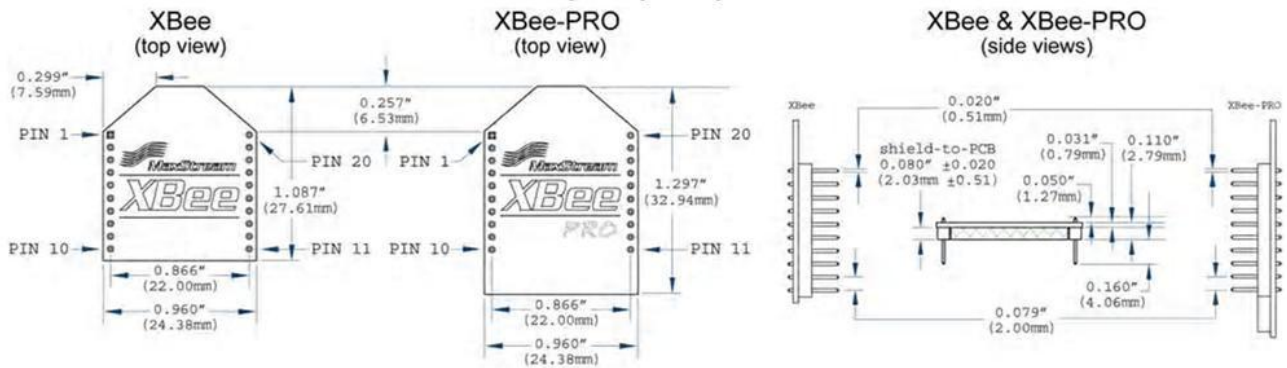
Additionally, European regulations stipulate an EIRP power maximum of 12.86 dBm (19 mW) for the XBee-PRO and 12.11 dBm for the XBee when integrating high-gain antennas.

\*\* When operating in Japan: Transmit power output is limited to 10 dBm. A special part number is required when ordering modules approved for use in Japan. Contact MaxStream for more information [call 1-801-765-9885 or send e-mails to sales@maxstream.net].

Antenna Options: The ranges specified are typical when using the integrated Whip (1.5 dBi) and Dipole (2.1 dBi) antennas. The Chip antenna option provides advantages in its form factor; however, it typically yields shorter range than the Whip and Dipole antenna options when transmitting outdoors. For more information, refer to the "XBee Antenna" application note located on MaxStream's web site (<http://www.maxstream.net/support/knowledgebase/article.php?kb=153>).

### 1.3. Mechanical Drawings

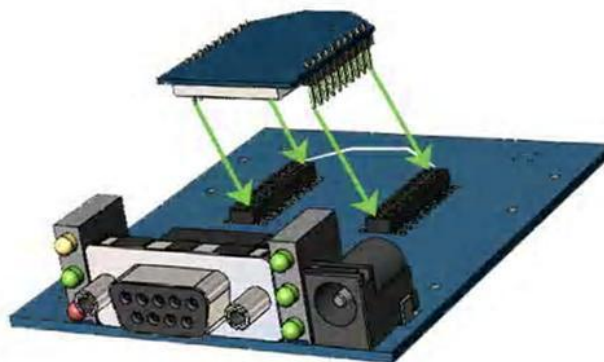
Figure 1-01. Mechanical drawings of the XBee/XBee-PRO OEM RF Modules (antenna options not shown)  
 The XBee and XBee-PRO RF Modules are pin-for-pin compatible.



### 1.4. Mounting Considerations

The XBee/XBee-PRO RF Module was designed to mount into a receptacle (socket) and therefore does not require any soldering when mounting it to a board. The XBee Development Kits contain RS-232 and USB interface boards which use two 20-pin receptacles to receive modules.

Figure 1-02. XBee Module Mounting to an RS-232 Interface Board.



The receptacles used on MaxStream development boards are manufactured by Century Interconnect. Several other manufacturers provide comparable mounting solutions; however, MaxStream currently uses the following receptacles:

- Through-hole single-row receptacles - Samtec P/N: MMS-110-01-L-SV (or equivalent)
- Surface-mount double-row receptacles - Century Interconnect P/N: CPRMSL20-D-0-1 (or equivalent)
- Surface-mount single-row receptacles - Samtec P/N: SMM-110-02-SM-S

MaxStream also recommends printing an outline of the module on the board to indicate the orientation the module should be mounted.

## 1.5. Pin Signals

Figure 1-03. XBee/XBee-PRO RF Module Pin Numbers

(top sides shown - shields on bottom)



Table 1-02. Pin Assignments for the XBee and XBee-PRO Modules

(Low-asserted signals are distinguished with a horizontal line above signal name.)

Pin #	Name	Direction	Description
1	VCC	-	Power supply
2	DOUT	Output	UART Data Out
3	DIN / <u>CONFIG</u>	Input	UART Data In
4	<u>DO8*</u>	Output	Digital Output 8
5	<u>RESET</u>	Input	Module Reset (reset pulse must be at least 200 ns)
6	PWM0 / RSSI	Output	PWM Output 0 / RX Signal Strength Indicator
7	PWM1	Output	PWM Output 1
8	[reserved]	-	Do not connect
9	<u>DTR / SLEEP_RQ / DI8</u>	Input	Pin Sleep Control Line or Digital Input 8
10	GND	-	Ground
11	AD4 / DIO4	Either	Analog Input 4 or Digital I/O 4
12	<u>CTS / DIO7</u>	Either	Clear-to-Send Flow Control or Digital I/O 7
13	<u>ON / SLEEP</u>	Output	Module Status Indicator
14	VREF	Input	Voltage Reference for A/D Inputs
15	<u>Associate / AD5 / DIO5</u>	Either	Associated Indicator, Analog Input 5 or Digital I/O 5
16	<u>RTS / AD6 / DIO6</u>	Either	Request-to-Send Flow Control, Analog Input 6 or Digital I/O 6
17	AD3 / DIO3	Either	Analog Input 3 or Digital I/O 3
18	AD2 / DIO2	Either	Analog Input 2 or Digital I/O 2
19	AD1 / DIO1	Either	Analog Input 1 or Digital I/O 1
20	AD0 / DIO0	Either	Analog Input 0 or Digital I/O 0

\* Function is not supported at the time of this release

### Design Notes:

- Minimum connections: VCC, GND, DOUT & DIN
- Minimum connections for updating firmware: VCC, GND, DIN, DOUT, RTS & DTR
- Signal Direction is specified with respect to the module
- Module includes a 50k  $\Omega$  pull-up resistor attached to RESET
- Several of the input pull-ups can be configured using the PR command
- Unused pins should be left disconnected

## 1.6. Electrical Characteristics

Table 1-03. DC Characteristics (VCC = 2.8 - 3.4 VDC)

Symbol	Characteristic	Condition	Min	Typical	Max	Unit
V <sub>IL</sub>	Input Low Voltage	All Digital Inputs	-	-	0.35 * VCC	V
V <sub>IH</sub>	Input High Voltage	All Digital Inputs	0.7 * VCC	-	-	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2 mA, VCC >= 2.7 V	-	-	0.5	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -2 mA, VCC >= 2.7 V	VCC - 0.5	-	-	V
I <sub>IIN</sub>	Input Leakage Current	V <sub>IN</sub> = VCC or GND, all inputs, per pin	-	0.025	1	μA
I <sub>IOZ</sub>	High Impedance Leakage Current	V <sub>IN</sub> = VCC or GND, all I/O High-Z, per pin	-	0.025	1	μA
TX	Transmit Current	VCC = 3.3 V	-	45 (XBee)    215 (PRO)	-	mA
RX	Receive Current	VCC = 3.3 V	-	50 (XBee)    55 (PRO)	-	mA
PWR-DWN	Power-down Current	SM parameter = 1	-	< 10	-	μA

Table 1-04. ADC Characteristics (Operating)

Symbol	Characteristic	Condition	Min	Typical	Max	Unit
V <sub>REFH</sub>	VREF - Analog-to-Digital converter reference range		2.08	-	V <sub>DDAD</sub>	V
I <sub>REF</sub>	VREF - Reference Supply Current	Enabled	-	200	-	μA
		Disabled or Sleep Mode	-	< 0.01	0.02	μA
V <sub>INDC</sub>	Analog Input Voltage <sup>1</sup>		V <sub>SSAD</sub> - 0.3	-	V <sub>DDAD</sub> + 0.3	V

1. Maximum electrical operating range, not valid conversion range.

Table 1-05. ADC Timing/Performance Characteristics<sup>1</sup>

Symbol	Characteristic	Condition	Min	Typical	Max	Unit
R <sub>AS</sub>	Source Impedance at Input <sup>2</sup>		-	-	10	kΩ
V <sub>AIN</sub>	Analog Input Voltage <sup>3</sup>		V <sub>REFL</sub>		V <sub>REFH</sub>	V
RES	Ideal Resolution (1 LSB) <sup>4</sup>	2.08V ≤ V <sub>DDAD</sub> ≤ 3.6V	2.031	-	3.516	mV
DNL	Differential Non-linearity <sup>5</sup>		-	±0.5	±1.0	LSB
INL	Integral Non-linearity <sup>6</sup>		-	±0.5	±1.0	LSB
E <sub>ZS</sub>	Zero-scale Error <sup>7</sup>		-	±0.4	±1.0	LSB
E <sub>FS</sub>	Full-scale Error <sup>8</sup>		-	±0.4	±1.0	LSB
E <sub>IL</sub>	Input Leakage Error <sup>9</sup>		-	±0.05	±5.0	LSB
E <sub>TU</sub>	Total Unadjusted Error <sup>10</sup>		-	±1.1	±2.5	LSB

1. All ACCURACY numbers are based on processor and system being in WAIT state (very little activity and no IO switching) and that adequate low-pass filtering is present on analog input pins (filter with 0.01 μF to 0.1 μF capacitor between analog input and VREFL). Failure to observe these guidelines may result in system or microcontroller noise causing accuracy errors which will vary based on board layout and the type and magnitude of the activity.

Data transmission and reception during data conversion may cause some degradation of these specifications, depending on the number and timing of packets. It is advisable to test the ADCs in your installation if best accuracy is required.

2. R<sub>AS</sub> is the real portion of the impedance of the network driving the analog input pin. Values greater than this amount may not fully charge the input circuitry of the ATD resulting in accuracy error.

3. Analog input must be between VREFL and VREFH for valid conversion. Values greater than VREFH will convert to \$3FF.

4. The resolution is the ideal step size or 1LSB = (VREFH - VREFL)/1024

5. Differential non-linearity is the difference between the current code width and the ideal code width (1LSB). The current code width is the difference in the transition voltages to and from the current code.

6. Integral non-linearity is the difference between the transition voltage to the current code and the adjusted ideal transition voltage for the current code. The adjusted ideal transition voltage is (Current Code - 1/2) \* (1 / ((VREFH + EFS) - (VREFL + EZS))).

7. Zero-scale error is the difference between the transition to the first valid code and the ideal transition to that code. The ideal transition voltage to a given code is (Code - 1/2) \* (1 / (VREFH - VREFL)).

8. Full-scale error is the difference between the transition to the last valid code and the ideal transition to that code. The ideal transition voltage to a given code is (Code - 1/2) \* (1 / (VREFH - VREFL)).

9. Input leakage error is error due to input leakage across the real portion of the impedance of the network driving the analog pin. Reducing the impedance of the network reduces this error.

10. Total unadjusted error is the difference between the transition voltage to the current code and the ideal straight-line transfer function. This measure of error includes inherent quantization error (1/2LSB) and circuit error (differential, integral, zero-scale, and full-scale) error. The specified value of E<sub>TU</sub> assumes zero E<sub>IL</sub> (no leakage or zero real source impedance).